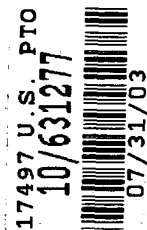


SIEMENS

Express Mail Label No.: EV 339090155US

UTILITY PATENT

Case Docket No.: 2003P10694US



Mail Stop PATENT APPLICATION
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 P.O. Box 1450
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Date: July 31, 2003

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Sir:

Transmitted herewith for filing is the patent application of:

Inventor(s): Jay Alan Morrison
 Gary Brian Merrill

For (title): BOND ENHANCEMENT FOR THERMALLY INSULATED CERAMIC
 MATRIX COMPOSITE MATERIALS

This application includes:

18 pages: specification, claims, and abstract
6 sheets of drawings containing 13 figures

Also enclosed is:

- ☒ Declaration and Power of Attorney
☒ An assignment of the invention to Siemens Westinghouse Power Corporation
☐ A certified copy of a _____ application.
☒ Information Disclosure Statement pursuant to 37 CFR 1.56.

The filing fee has been calculated as shown below:

					FEE
BASIC FEE OTHER THAN SMALL ENTITY					\$ 750
TOTAL CLAIMS		EXTRA			
<u>24</u> - 20	=	<u>4</u>	x \$18.00	=	\$ <u>72</u>
INDEP CLAIMS					
<u>4</u> - 3	=	<u>1</u>	x \$84.00	=	\$ <u>84</u>
*MULTIPLE DEPENDENT CLAIM PRESENTED + \$72					= \$ <u>0</u>
TOTAL					\$ 906

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All correspondence related to this application should be sent to:

Siemens Corporation
Intellectual Property Department
170 Wood Avenue South
Iselin, NJ 08830
Tel. (732) 321-3026

Dated: July 31, 2003



David G. Maire
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(407)-926-7704

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Application of)
Applicants: Jay Alan Morrison, et al)
Application No.: Not Assigned)
Filing Date: Simultaneously Herewith)
For: BOND ENHANCEMENT FOR THERMALLY)
INSULATED CERAMIC MATRIX)
COMPOSITE MATERIALS)

Attorney Docket: 2003P10694US

Mail Stop Patent Application
Commissioner for Patents
P.O. Box 1450
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Sir:

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Date of Deposit: July 31, 2003

I hereby certify that the attached patent application, formal papers, and drawings were deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 CFR 1.10 on the date indicated above and is addressed to: Mail Stop Patent Application, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

Respectfully submitted,



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